

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application:
Rajeev Joshi et al.

Serial No.: 10/731,453

Filed: December 9, 2003

For: WAFER-LEVEL CHIP SCALE PACKAGE AND
METHOD FOR FABRICATING AND USING THE
SAME

Confirmation No. 4432

Group Art Unit: 2891

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Commissioner for Patents
P.O. Box 1450
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Sir:

REQUEST FOR RECONSIDERATION

In response to the Office Action mailed on August 20, 2007, Applicants respectfully request reconsideration of this application in light of the following remarks.

Remarks begin on page 2 of this paper.